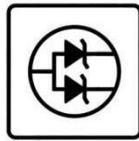
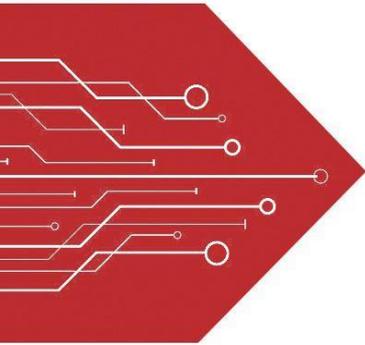
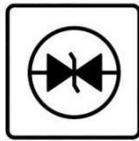


MSKSEMI

SEMICONDUCTOR



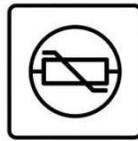
ESD



TVS



TSS



MOV



GDT

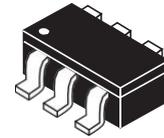


PLED

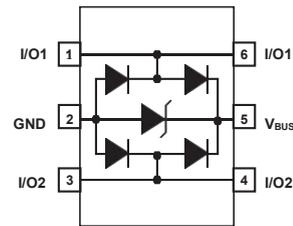
Product data sheet

Features

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: ±30kV
 - Contact discharge: ±30kV
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 6A (8/20µs)
- RoHS Compliant



SOT23-6L
USBLC6-2SC6



Applications

- USB 2.0 interface
- 10/100 Ethernet
- Personal digital assistants (PDA's)
- Notebooks, Desktops and Servers
- Portable instrumentation
- Digital cameras

Mechanical Characteristics

- Package: SOT23-6 Lead
- Finish: Matte Tin
- UL Flammability Classification Rating 94V-0
- Pb-Free, Halogen Free, RoHS/WEEE Compliant

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	Ppk	150	W
Peak Pulse Current (8/20µs)	Ipp	6	A
ESD per IEC 61000-4-2 (Air)	VESD	±30	kV
ESD per IEC 61000-4-2 (Contact)		±30	
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	Tstg	-55 to +150	°C

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse stand-off voltage	V_{RWM}				5	V
Reverse breakdown voltage	V_{BR}	$I_{BR}=1\text{mA}$	6		9	V
Reverse leakage current	I_R	$V_R=5\text{V}$			0.1	μA
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=1\text{A}$			10	V
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=6\text{A}$			15	V
Junction capacitance	C_J	0Vdc, f=1MHz Between I/O pins and GND		0.8	1	pF
	C_J	0Vdc, f=1MHz I/O to I/O		0.35	0.4	pF

Typical Characteristics

Fig1. 8/20 μs Pulse Waveform

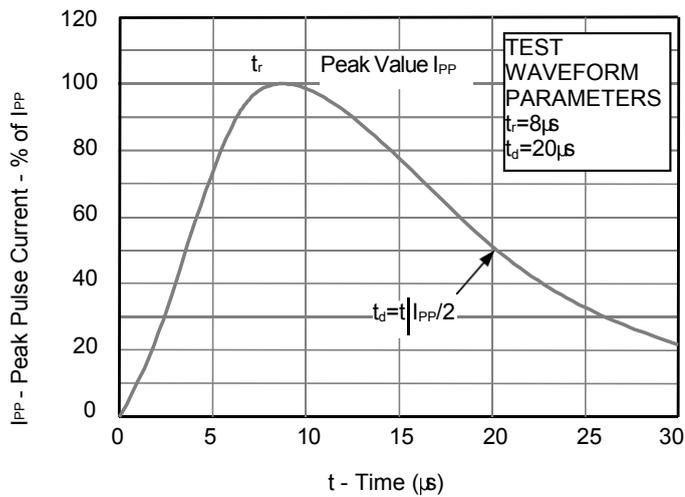


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

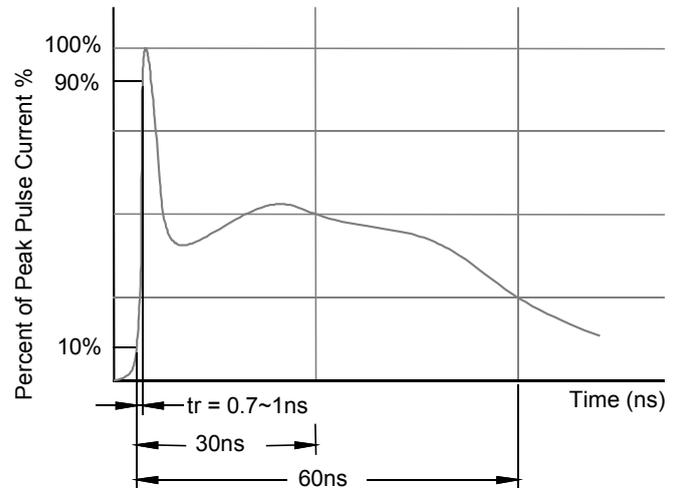
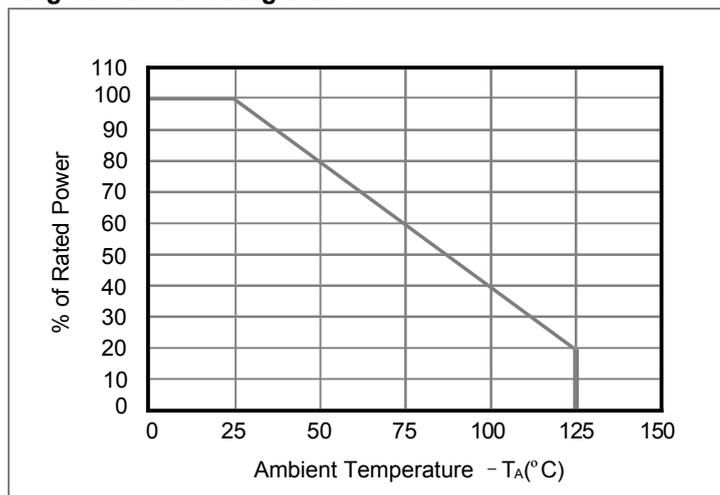
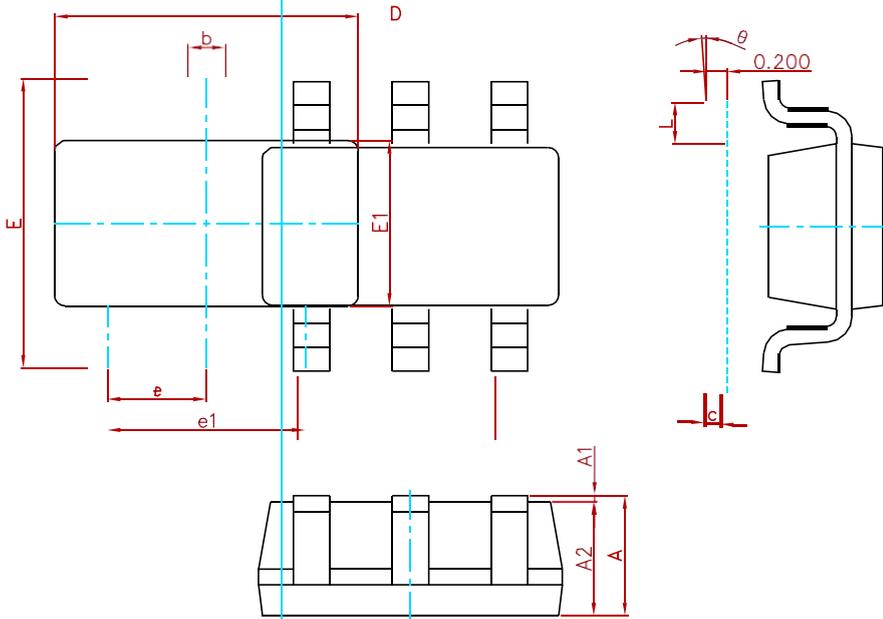


Fig3. Power Derating Curve

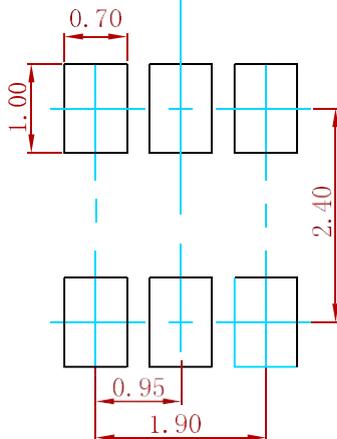


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MSUSBLC6-2SC6	SOT-23-6	3000

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